

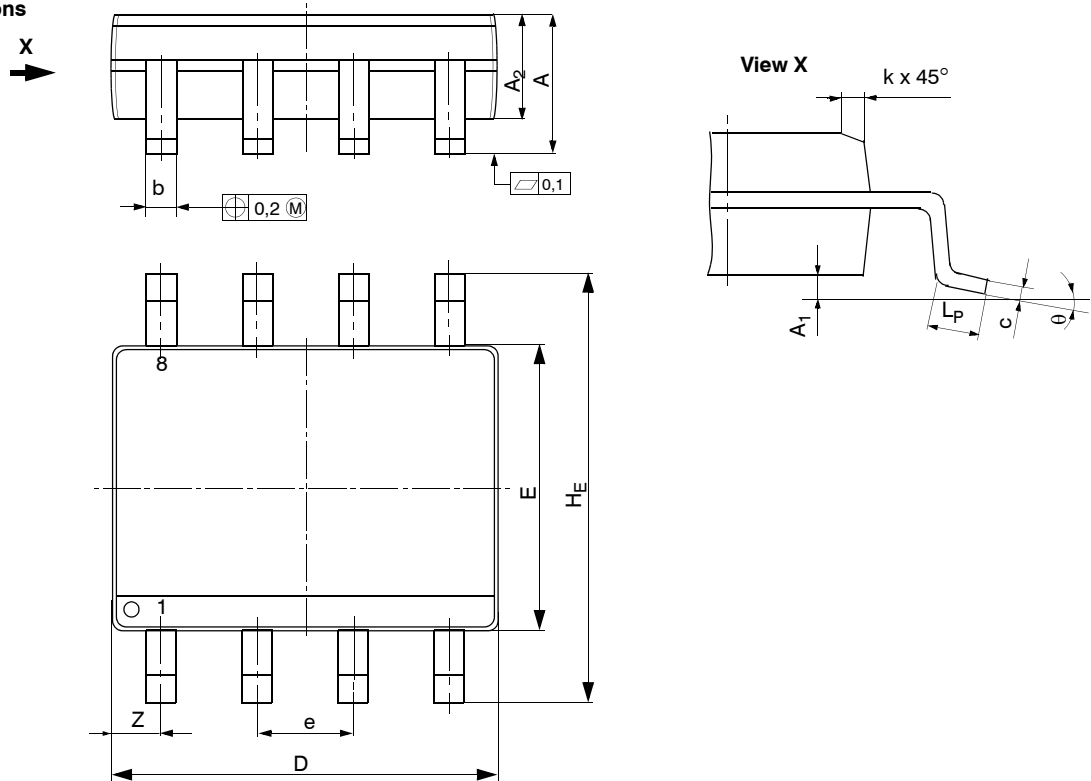
	Package SOP8 (150 mil)	MDS 726
---	----------------------------------	--------------------------

Supersedes
Edition 11.95

Dimensions in millimetres

Based on IEC 191-2Q: Type 076E35 B

1 Dimensions



Dimensions of Sub-Group B1	
$A_{\max}$	1,95
$b_{P\min}$	0,35
$b_{P\max}$	0,49
e_{nom}	1,27
$H_{E\min}$	5,80
$H_{E\max}$	6,30
$L_{P\min}$	0,40
$Z_{\max}$	0,635

- 2 Weight** $\leq 0,3 \text{ g}$
3 Package Body Material Low Stress Epoxy
4 Lead Material FeNi-Alloy or Cu-Alloy
5 Lead Finish solder plating
6 Lead Form Z-bends

Dimensions of Sub-Group C1	
$A_{\min}$	1,55
$A_{1\min}$	0,10
$A_{1\max}$	0,30
$A_{2\min}$	1,40
$A_{2\max}$	1,80
$c_{\min}$	0,15
$c_{\max}$	0,25
$D_{\min}^*$	4,80
$D_{\max}^*$	5,00
$E_{\min}^*$	3,80
$E_{\max}^*$	4,00
$k_{\min}$	0,33
$\theta_{\min}$	0°
$\theta_{\max}$	8°

* without mold-flash

Zentrum Mikroelektronik Dresden		
Editor: signature by Schoder	Date: 06.01.2005	Doc-No. QS-000726-HD-03
Check: signature by Marx	Quality: signature by Tina Kochan	